



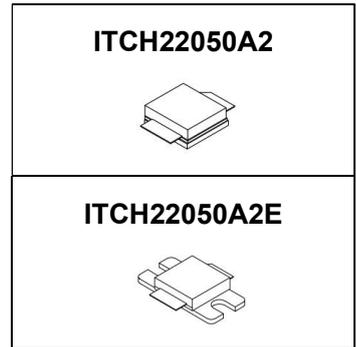
# 1800-2200MHz, 50W, 28V RF LDMOS FETs

## Description

The ITCH22050A2 is a 50-watt, internally-matched LDMOS FETs, designed for cellular and communication with frequencies from 1800 MHz to 2200 MHz. It can be used in Class AB/B and Class C for all typical modulation formats.

• Typical Performance (On Test Fixture with device soldered):

VDD = 28 Volts, IDQ = 400 mA, Pulse CW, Pulse Width=20 us, Duty cycle=10%



Freq (GHz)	Pulse CW Signal <sup>(1)</sup>			P <sub>avg</sub> =40.0dBm WCDMA Signal <sup>(2)</sup>		
	Gain_P1 (dB)	P3dB (dBm)	P3dB (W)	Gp (dB)	η <sub>D</sub> (%)	ACPR <sub>5M</sub> (dBc)
1.98	18.02	48.51	71.0	19.26	27.56	-34.11
1.995	17.84	48.38	68.8	19.47	27.93	-33.08
2.01	18.55	48.23	66.6	19.62	28.35	-33.61

## Features

- High Efficiency and Linear Gain Operations
- Integrated ESD Protection
- Internally Matched for Ease of Use
- Excellent thermal stability, low HCl drift
- Large Positive and Negative Gate/Source Voltage Range for Improved Class C Operation
- Pb-free, RoHS-compliant

**Table 1. Maximum Ratings**

Rating	Symbol	Value	Unit
Drain--Source Voltage	V <sub>DSS</sub>	65	Vdc
Gate--Source Voltage	V <sub>GS</sub>	-10 to +10	Vdc
Operating Voltage	V <sub>DD</sub>	+32	Vdc
Storage Temperature Range	T <sub>stg</sub>	-65 to +150	°C
Case Operating Temperature	T <sub>c</sub>	-55~+150	°C
Operating Junction Temperature	T <sub>j</sub>	+225	°C

**Table 2. Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction to Case T <sub>C</sub> = 87°C, T <sub>J</sub> =175°C, DC test	R <sub>θJC</sub>	1.8	°C/W

**Table 3. ESD Protection Characteristics**

Test Methodology	Class
Human Body Model (per JESD22--A114)	Class 2

**Table 4. Electrical Characteristics** (TA = 25 °C unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
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### DC Characteristics

Zero Gate Voltage Drain Leakage Current (V <sub>DS</sub> = 65V, V <sub>GS</sub> = 0 V)	I <sub>DSS</sub>			100	μA
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Zero Gate Voltage Drain Leakage Current ( $V_{DS} = 28\text{ V}$ , $V_{GS} = 0\text{ V}$ )	$I_{loss}$			1	$\mu\text{A}$
Gate--Source Leakage Current ( $V_{GS} = 10\text{ V}$ , $V_{DS} = 0\text{ V}$ )	$I_{loss}$			1	$\mu\text{A}$
Gate Threshold Voltage ( $V_{DS} = 28\text{ V}$ , $I_D = 450\ \mu\text{A}$ )	$V_{GS(th)}$		2.0		V
Gate Quiescent Voltage ( $V_{DD} = 28\text{ V}$ , $I_D = 400\text{ mA}$ , Measured in Functional Test)	$V_{GS(Q)}$		2.8		V

**Functional Tests** (In Innegration Test Fixture, 50 ohm system)  $V_{DD} = 28\text{ Vdc}$ ,  $I_{DQ} = 400\text{ mA}$ ,  $f = 2000\text{ MHz}$ , CW Signal Measurements.

Power Gain @ $P_{1dB}$	$G_p$		18		dB
1 dB Compression Point	$P_{-1dB}$		47		W
Drain Efficiency@ $P_{1dB}$	$\eta_D$		55		%
Input Return Loss	IRL		-7		dB

**Load Mismatch (In Innegration Test Fixture, 50 ohm system):**  $V_{DD} = 28\text{ Vdc}$ ,  $I_{DQ} = 400\text{ mA}$ ,  $f = 2000\text{ MHz}$

VSWR 10:1 at 50W pulse CW Output Power	No Device Degradation
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### TYPICAL CHARACTERISTICS

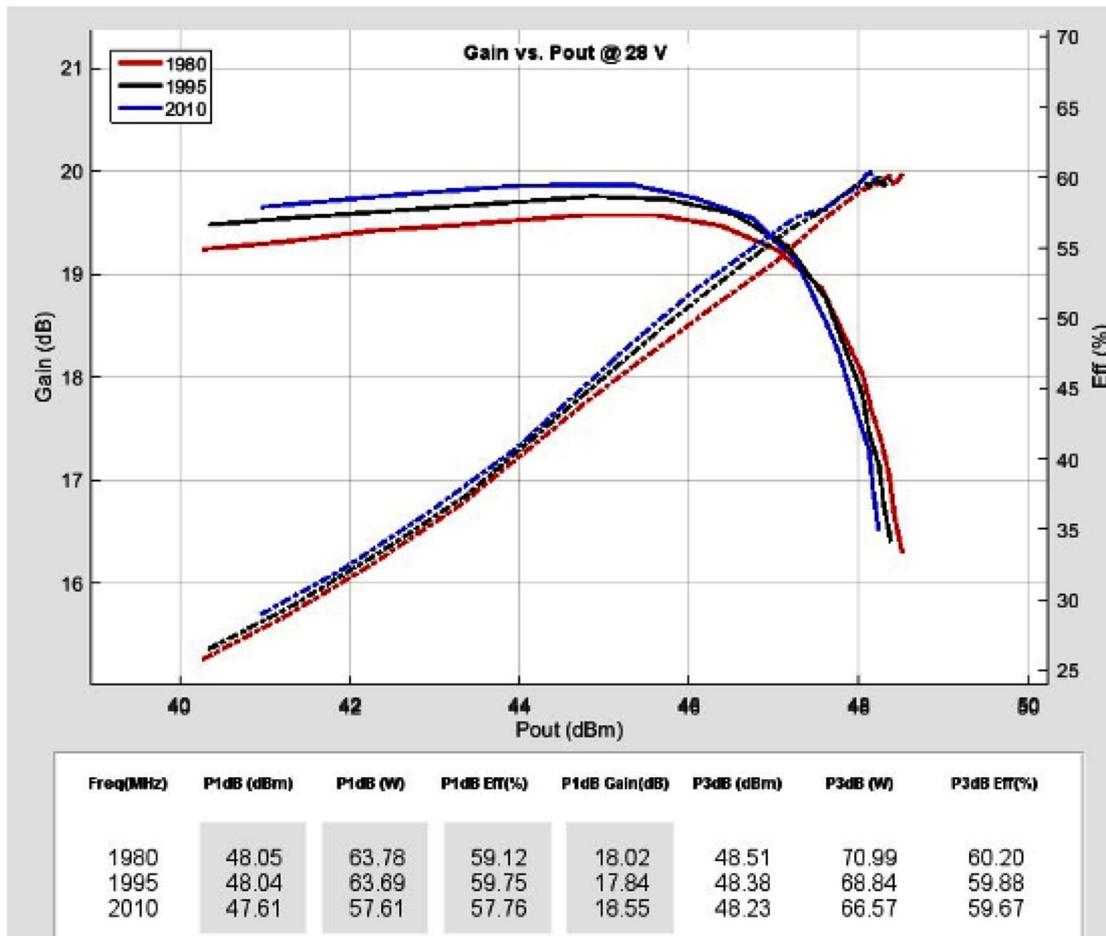


Figure 2. Power Gain and Drain Efficiency as function of Power Out



Figure 3. S11 and S21 of Network analyzer output

### Reference Circuit of Test Fixture Assembly Diagram

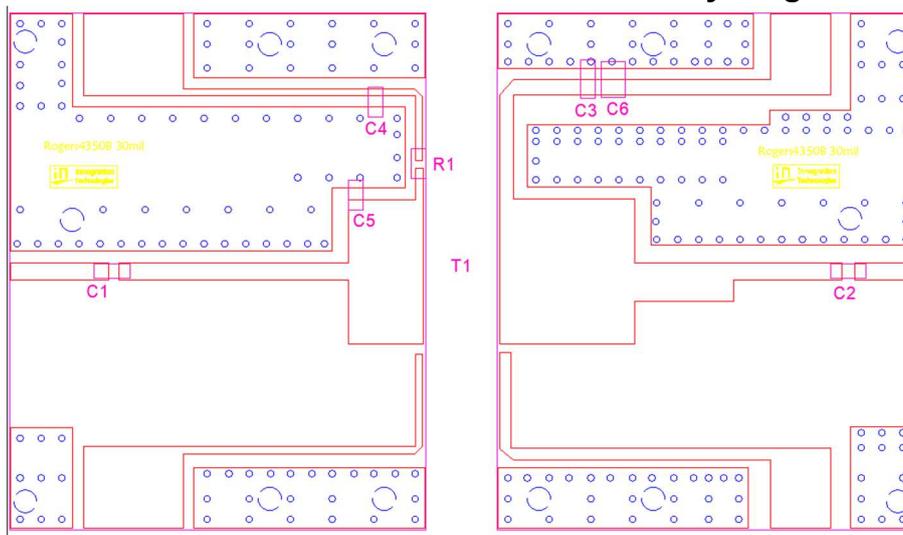


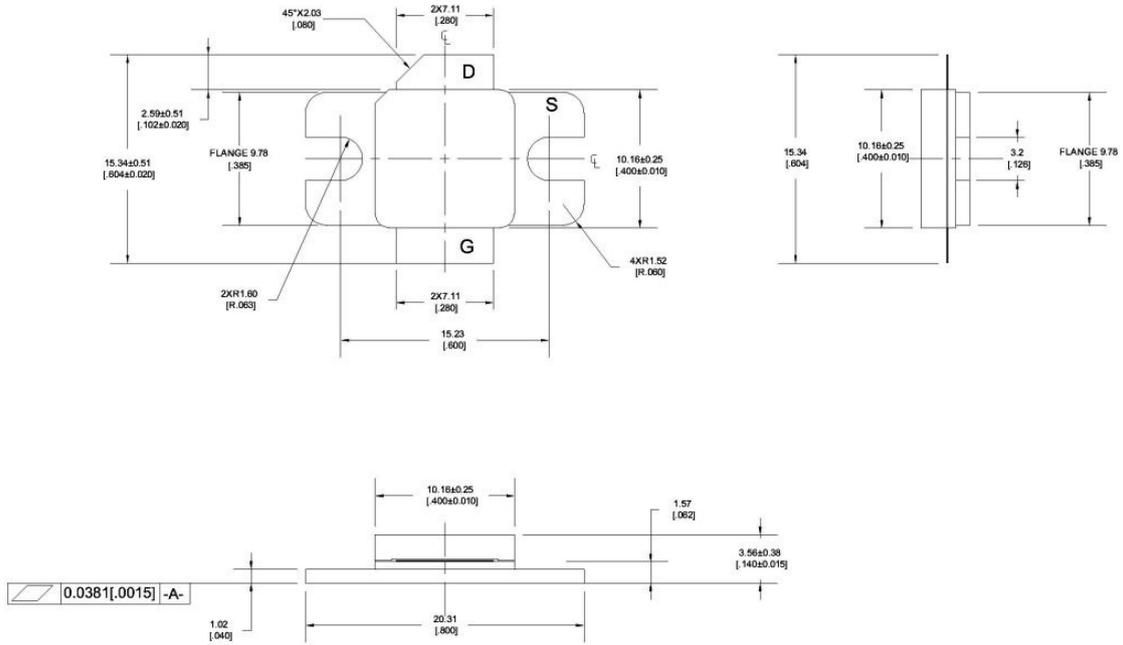
Table 5. Test Circuit Component Designations and Values

Part	Quantity	Description	Part Number	Manufacture
C1,C2,C3,C4	4	20pF High Q Capacitor	251SHS200BSE	TEMEX
C5	1	1.5pF High Q Capacitor	251SHS1R5BSE	TEMEX
C6	1	10uF MLCC	GRM32EC72A106M E05	Murata
R1	1	10 Ω Power Resistor	ESR03EZPF100	ROHM
T1	1	50W LDMOS Transistor	ITCH22050A2E	Innogrator



### Package Outline

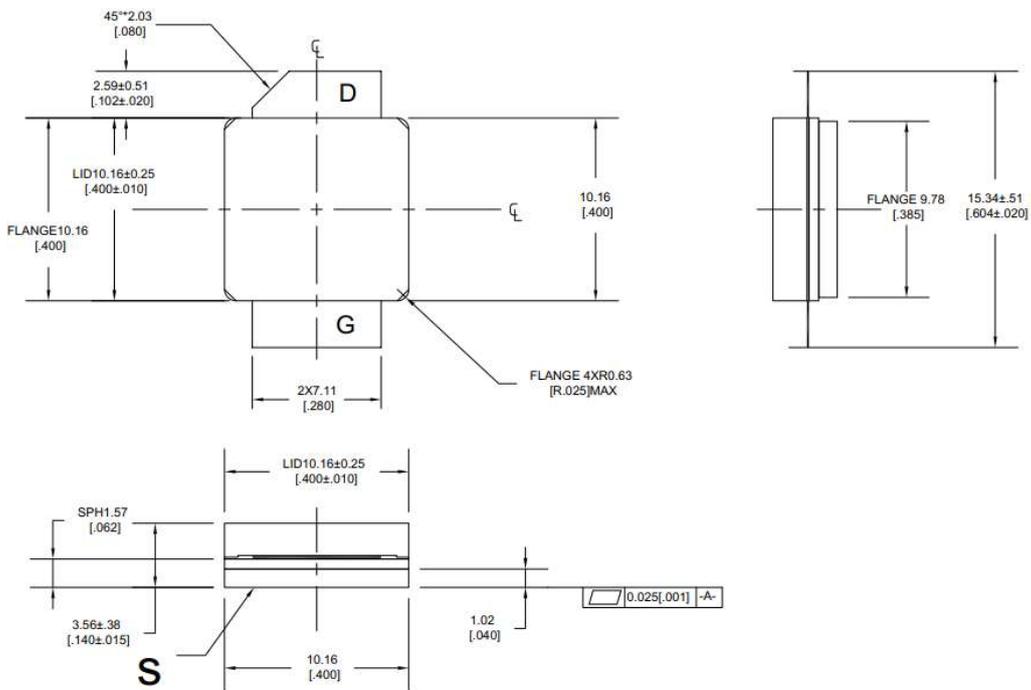
#### Eared Flanged ceramic package; 2 leads (A2E)



Unit: mm [inch]

Tolerance .xx +/- 0.01 .xxx +/- 0.005 inches

#### Earless Flanged ceramic package; 2 leads (A2)



Unit: mm [inch]

Tolerance .xx +/- 0.01 .xxx +/- 0.005 inches



## Revision history

Table 5. Document revision history

Date	Revision	Datasheet Status
2023/11/2	Rev 1.0	Product Datasheet

Application data based on LWH-23-20

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